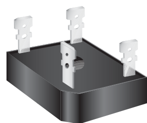
Material Composition Specification
Case FP



Device average mass . . . . 18.0 g
Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.242%	43.58	Si	7440-21-3	0.23%	41.4	2,299
				Ni	7440-02-0	0.012%	2.18	121
leadframe	copper	24.26%	4,367	Cu	7440-50-8	24.26%	4,367	242,611
plating	nickel	0.03%	5.4	Ni	7440-02-0	0.03%	5.4	300
die attach	high temperature solder	13.245%	2,384	Pb	7439-92-1	0.005%	0.945	53
				Sn	7440-31-5	0.0001%	0.05	3
				Cu	7440-50-8	13.24%	2,383	132,392
encapsulation	EMC with aluminum heatsink	62.23%	11,200	epoxy resin	Proprietary	53.57%	9,640	535,556
				Al	7429-90-5	8.67%	1,560	86,667

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.